

# HT8KC5

60V Nch+Nch Power MOSFET

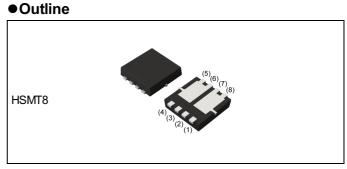
V <sub>DSS</sub>	60V
R <sub>DS(on)</sub> (Max.)	90mΩ
I <sub>D</sub>	±10A
P <sub>D</sub>	13W

## Features

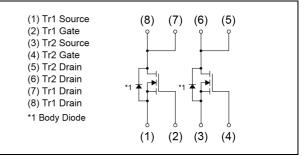
- 1) Low on resistance
- 2) High Power small mold Package (HSMT8)
- 3) Pb-free plating ; RoHS compliant
- 4) Halogen Free

Application

Switching



## Inner circuit



### Packaging specifications

	Packing	Embossed Tape
	Reel size (mm)	330
Туре	Tape width (mm)	12
	Quantity (pcs)	3000
	Taping code	TB1
	Marking	HT8KC5

### • Absolute maximum ratings ( $T_a = 25^{\circ}C$ ,unless otherwise specified) <Tr1 and Tr2>

Paramete	Symbol	Value	Unit	
Drain - Source voltage	V <sub>DSS</sub>	60	V	
Continuous drain surrent	$T_c = 25^{\circ}C$	I <sub>D</sub> *1	±10	Α
Continuous drain current	T <sub>a</sub> = 25°C	I <sub>D</sub>	±3.5	Α
Pulsed drain current	I <sub>DP</sub> *2	±14	Α	
Gate - Source voltage	V <sub>GSS</sub>	±20	V	
Avalanche current, single pulse	I <sub>AS</sub> *3	3.5	Α	
Avalanche energy, single pulse	E <sub>AS</sub> *3	1.0	mJ	
Dower dissinction (total)	P <sub>D</sub> <sup>*1</sup>	13	14/	
Power dissipation (total)		P <sub>D</sub> *4	2.0	W
Junction temperature	Tj	150	°C	
Operating junction and storage to	T <sub>stg</sub>	-55 to +150	°C	

## Thermal resistance

Perameter	Symbol	Values			Unit
Parameter	Symbol	Min.	Тур.	Max.	Unit
Thermal resistance, junction - case	R <sub>thJC</sub> <sup>*1</sup>	-	-	9,4	°C/W
Thermal resistance, junction - ambient	R <sub>thJA</sub> *4	-	-	62.5	°C/W

## •Electrical characteristics (T<sub>a</sub> = 25°C) <Tr1 and Tr2>

Devenuetor	C: make al	Symbol Conditions		Values			
Parameter	Symbol Conditions		Min.	Тур.	Max.	Unit	
Drain - Source breakdown voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = 1mA	60	-	-	V	
Breakdown voltage	ΔV <sub>(BR)DSS</sub>	I <sub>D</sub> = 1mA		38.9		mV/°C	
temperature coefficient	ΔTj	referenced to 25°C	-	30.9	-	IIIV/ C	
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> = 60V, V <sub>GS</sub> = 0V	-	-	1	μA	
Gate - Source leakage current	I <sub>GSS</sub>	V <sub>GS</sub> = ±20V, V <sub>DS</sub> = 0V	-	-	±100	nA	
Gate threshold voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 1mA	1.0	-	2.5	V	
Gate threshold voltage	$\Delta V_{GS(th)}$	I <sub>D</sub> = 1mA		47		~~\//°C	
temperature coefficient	Δ Τ <sub>j</sub>	referenced to 25°C	-	-4.7	-	mV/°C	
Static drain - source	D *5	V <sub>GS</sub> = 10V, I <sub>D</sub> = 3.5A	-	69	90		
on - state resistance	R <sub>DS(on)</sub> *5	V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 3.5A	-	99	139	mΩ	
Gate resistance	R <sub>G</sub>	-	-	2.7	-	Ω	
Forward Transfer Admittance	Y <sub>fs</sub>   <sup>*5</sup>	V <sub>DS</sub> = 5V, I <sub>D</sub> = 3.5A	2.3	-	-	S	

\*1 T<sub>c</sub> = 25°C, Limited only by maximum temperature allowed.

- \*2 Pw  $\leq$  10µs, Duty cycle  $\leq$  1%
- \*3 L  $\simeq$  0.1mH, V\_{DD} = 30V, R\_G = 25 $\Omega$ , Starting T\_j = 25°C Fig.3-1,3-2
- \*4 Mounted on a Cu board (40×40×0.8mm)
- \*5 Pulsed



## •Electrical characteristics ( $T_a = 25^{\circ}C$ ) <Tr1 and Tr2>

Deremeter	Cump of	Conditions		l loit		
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Input capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0V	-	135	-	
Output capacitance	C <sub>oss</sub>	V <sub>DS</sub> = 30V	-	38	-	pF
Reverse transfer capacitance	C <sub>rss</sub>	f = 1MHz	-	6	-	
Turn - on delay time	t <sub>d(on)</sub> *5	$V_{DD} \simeq 30V, V_{GS}$ = 10V	-	5.3	-	
Rise time	t <sub>r</sub> *5	I <sub>D</sub> = 1.75A	-	5.0	-	
Turn - off delay time	$t_{d(off)}^{*5}$	R <sub>L</sub> = 17.1Ω	-	13.0	-	ns
Fall time	t <sub>f</sub> *5	R <sub>G</sub> = 10Ω	-	3.1	-	

## •Gate charge characteristics (T<sub>a</sub> = 25°C) <Tr1 and Tr2>

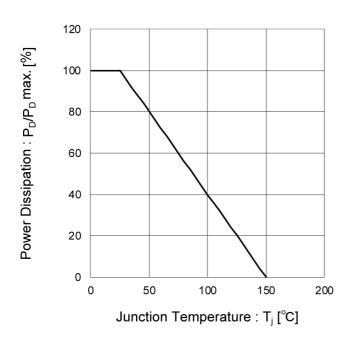
Deremeter	Symbol	Conditions		Values			l loc'h
Parameter	Symbol Conditions		Min.	Тур.	Max.	Unit	
Total materials and	<b>O</b> *5		V <sub>GS</sub> = 10V	-	3.1	-	
Total gate charge	$Q_g^{*5}$	V <sub>DD</sub> ≃ 30V		-	1.7	-	
Gate - Source charge	$Q_{gs}^{*5}$	I <sub>D</sub> = 3.5A	V <sub>GS</sub> = 4.5V	-	0.9	-	nC
Gate - Drain charge	${\sf Q_{gd}}^{*5}$			-	0.3	-	

## •Body diode electrical characteristics (Source-Drain) (T<sub>a</sub> = 25°C)

<Tr1 and Tr2>

Parameter	Symbol	Conditions		Unit		
	Symbol	Conditions	Min.	Тур.	Max.	Unit
Continuous forward current	۱ <sub>s</sub>	$T = 25^{\circ}$	-	-	1.67	•
Pulse forward current	I <sub>SP</sub> *2	T <sub>a</sub> = 25℃	-	-	14	A
Forward voltage	$V_{SD}^{*5}$	V <sub>GS</sub> = 0V, I <sub>S</sub> = 1.67A	-	-	1.2	V
Reverse recovery time	t <sub>rr</sub> *5	I <sub>S</sub> = 3.5A, V <sub>GS</sub> = 0V	-	23	-	ns
Reverse recovery charge	Q <sub>rr</sub> *5	di/dt = 100A/µs	-	20	-	nC





## Fig.1 Power Dissipation Derating Curve

Fig.2 Maximum Safe Operating Area

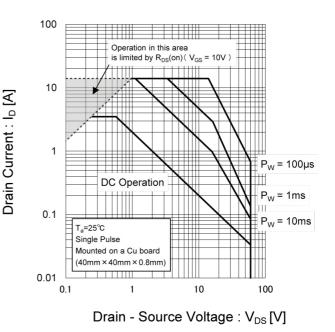
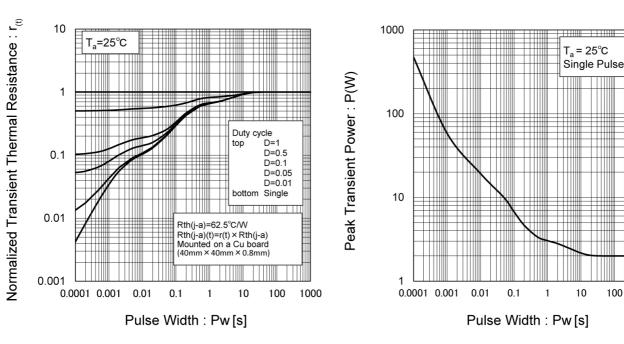


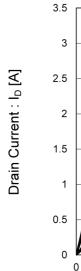
Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

Fig.4 Single Pulse Maximum Power Dissipation

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1000



0.1

## Fig.5 Typical Output Characteristics(I)

V<sub>GS</sub>= 10V

V<sub>GS</sub>= 4.5V

T<sub>a</sub>=25℃

Pulsed

V<sub>GS</sub>= 3.0V

 $V_{GS} = 2.0V$ 

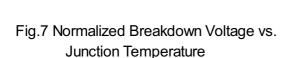
1

V<sub>GS</sub>= 4.0V

Drain Current : I<sub>D</sub> [A]

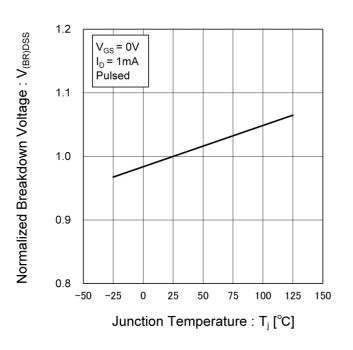
#### 3.5 T<sub>a</sub>=25°C V<sub>GS</sub>= 10V Pulsed 3 =V<sub>GS</sub>= 4.5V -V<sub>GS</sub>= 4.0V 2.5 2 1.5 V<sub>GS</sub>= 3.0V 1 0.5 V<sub>GS</sub>= 2.0V 0 2 3 5 6 0 1 4 7 8 9 10 Drain - Source Voltage : V<sub>DS</sub> [V]

## Fig.6 Typical Output Characteristics(II)

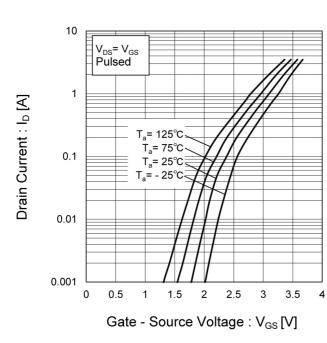


0.2 0.3 0.4 0.5 0.6 0.7 0.8 0.9

Drain - Source Voltage : V<sub>DS</sub> [V]







## Fig.8 Typical Transfer Characteristics

Fig.9 Gate Threshold Voltage vs. Junction Temperature

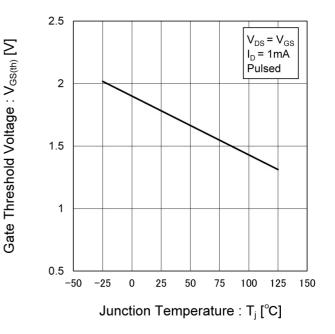
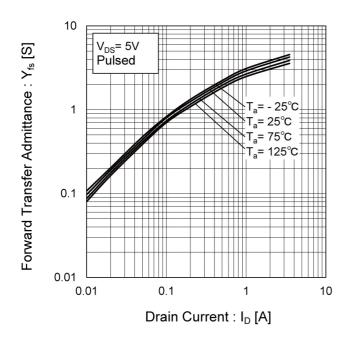


Fig.10 Forward Transfer Admittance vs. Drain Current





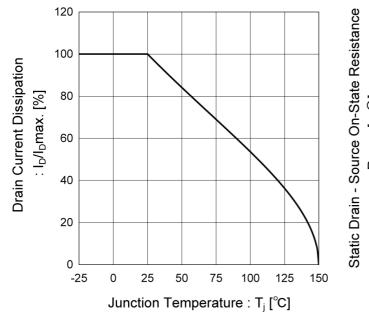


Fig.11 Drain Current Derating Curve

Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage

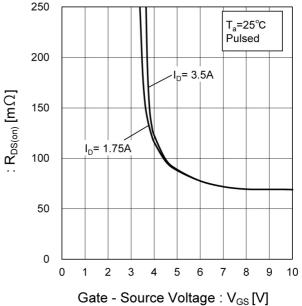
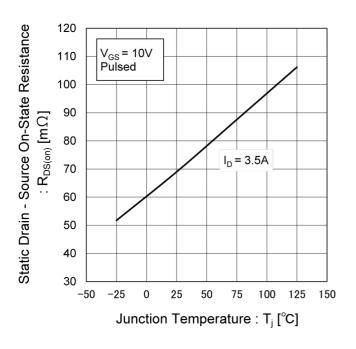


Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature





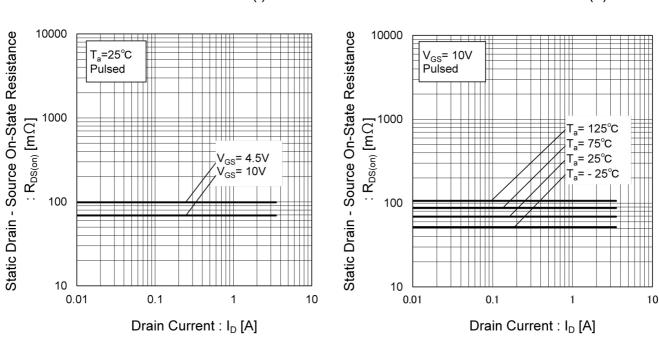
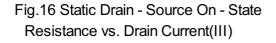
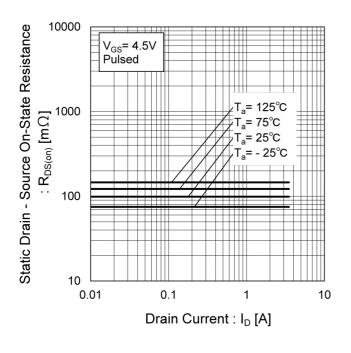


Fig.14 Static Drain - Source On - State Resistance vs. Drain Current(I) Fig.15 Static Drain - Source On - State Resistance vs. Drain Current(II)







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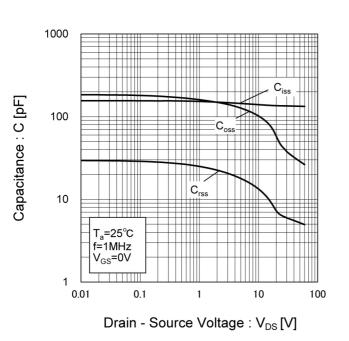


Fig.17 Typical Capacitances vs. Drain -Source Voltage

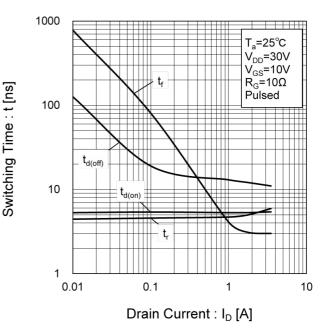
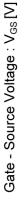


Fig.19 Typical Gate Charge



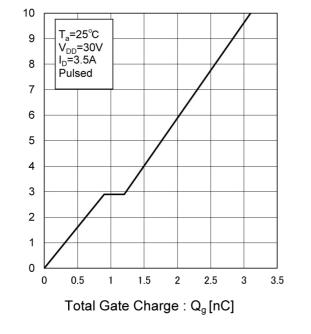
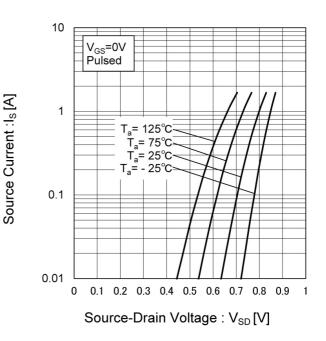


Fig.20 Source Current vs. Source Drain Voltage





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## •Measurement circuits <It is the same for the Tr1 and Tr2>

Fig.1-1 Switching Time Measurement Circuit

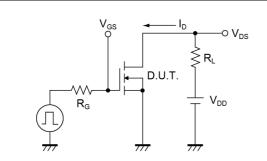


Fig.2-1 Gate Charge Measurement Circuit

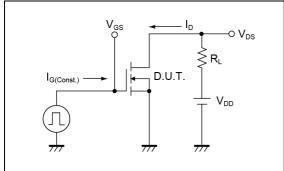


Fig.3-1 Avalanche Measurement Circuit

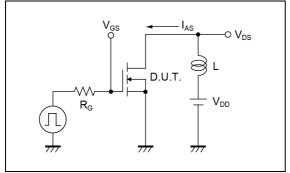


Fig.1-2 Switching Waveforms

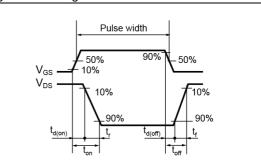
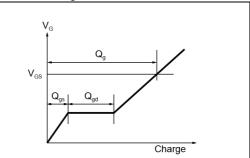
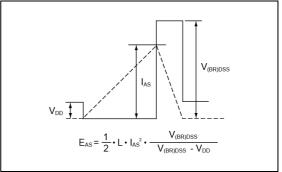


Fig.2-2 Gate Charge Waveform



#### Fig.3-2 Avalanche Waveform



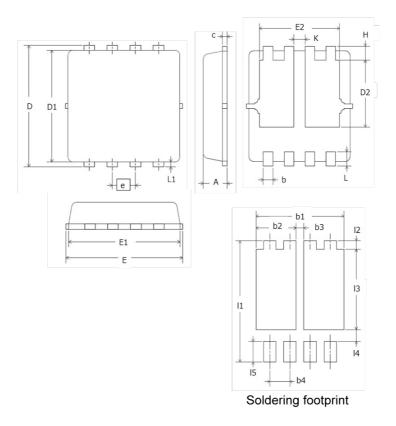
### Notice

This product might cause chip aging and breakdown under the large electrified environment. Please consider to design ESD protection circuit.



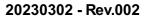
### Dimensions

HSMT8 (Dual)



DIM	Milimeters		Inc	hes	
	Min.	Max.	Min.	Max.	
A	0.70	0.80	0.028	0.031	
b	0.25	0.35	0.010	0.014	
с	0.10	0.25	0.004	0.010	
D	3.25	3.45	0.128	0.136	
D1	3.00	3.20	0.118	0.126	
D2	1.78	1.98	0.070	0.078	
E	3.20	3.40	0.126	0.134	
E1	3.00	3.20	0.118	0.126	
E2	2.39	2.59	0.094	0.102	
e	0.65		0.0	026	
Н	0.30	0.50	0.012	0.020	
L	0.30	0.50	0.012	0.020	
L1	0.1	13	0.005		
K	0.30	-	0.012	-	
DIM	Milim		Inches		
	No		Nom.		
1		3.55		140	
12	0.25		0.010		
13	2.35		0.093		
14	0.35			014	
15	0.60		0.024		
b1	2.83			111	
b2	1.29		0.051		
b3		25	0.010		
b4	0.4	0.40		016	

Dimension in mm / inches



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# Notice

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(Note1) Medical Equipment Classification of the Specific Applications
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JAPAN	USA	EU	CHINA
CLASSⅢ	CLASSI	CLASS II b	CLASSII
CLASSⅣ	CLASSII	CLASSⅢ	CLASSI

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  - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
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  - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
  - [f] Sealing or coating our Products with resin or other coating materials
  - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse, is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

#### Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

#### Precautions Regarding Application Examples and External Circuits

- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
- 2. You agree that application notes, reference designs, and associated data and information contained in this document are presented only as guidance for Products use. Therefore, in case you use such information, you are solely responsible for it and you must exercise your own independent verification and judgment in the use of such information contained in this document. ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of such information.

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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

#### Precaution for Storage / Transportation

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
  - [a] the Products are exposed to sea winds or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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